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Macromodelling and its Applications to Signal and Power Integrity

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Macromodelling and its Applications to Signal and Power Integrity

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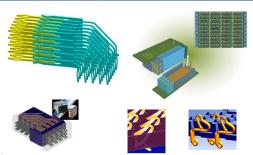


Outline

- Simulation of terminated interconnects
 Frequency and time-domain analysis
- Transient analysis
 - Convolution-based approaches
 - Direct circuit simulation (when possible)
 - Black-box passive macromodeling
- Black-box passive macromodeling
 - Rational curve fitting
 - Passivity enforcement
- An application example
- Coupled signal-power integrity analysis of a real board
- Conclusions

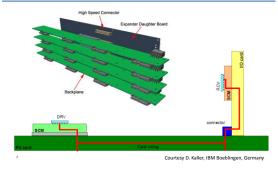


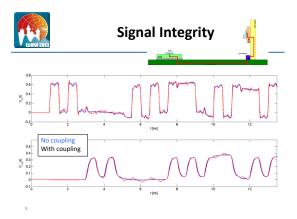
Interconnects: showcase





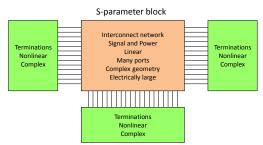
Interconnects: showcase

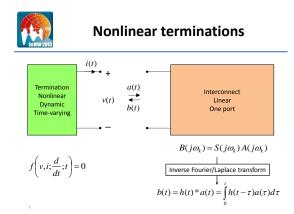






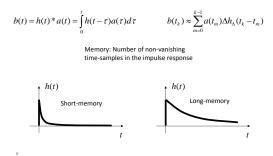
The objective

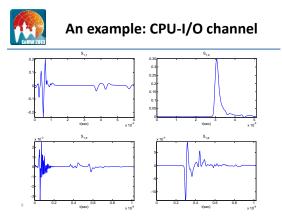






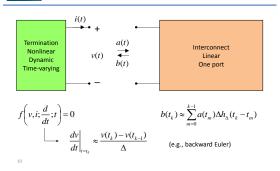
Discretizing convolution

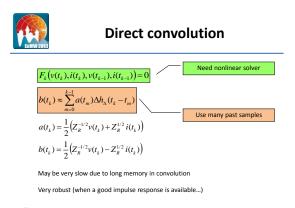






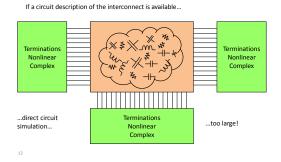
Direct convolution





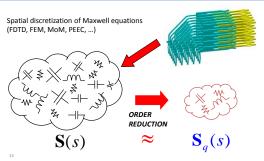


Direct circuit simulation



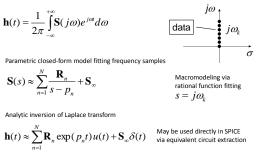


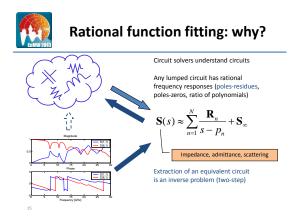
Model Order Reduction





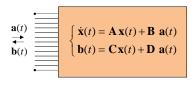
Black-Box Macromodeling



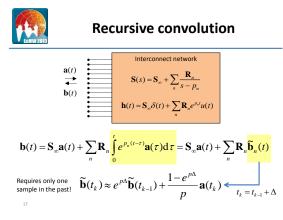




State-space realizations



$$\mathbf{S}(s) \approx \sum_{n=1}^{N} \frac{\mathbf{R}_n}{s - p_n} + \mathbf{S}_{\infty} = \mathbf{D} + \mathbf{C}(s\mathbf{I} - \mathbf{A})^{-1}\mathbf{B}$$



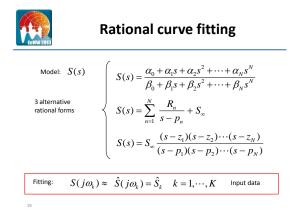


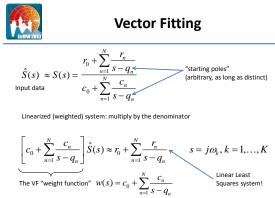
Macromodel implementations

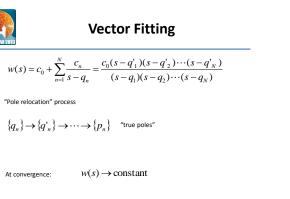
- Synthesize an equivalent circuit in SPICE format No access to SPICE kernel Must use standard circuit elements
 Direct SPICE implementation via recursive convolution Laplace element, most efficient
- 3. Other languages for mixed-signal analyses

Verilog-AMS,	VHDL-AMS,
--------------	-----------

Equation-based		CPU time		
	Standard convolution	389 seconds		
Example: board with 13 ports	Equivalent circuit	180 seconds		
18	Recursive convolution	5.8 seconds		

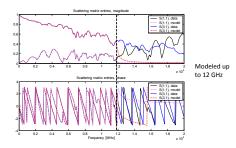








High-speed connector, measured





Advanced VF formulations

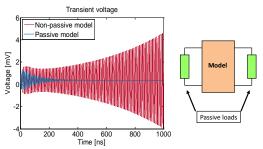
- Time-domain Vector Fitting

 Processes time samples instead of frequency samples
- •
- Further improvement in matrix conditioning using orthonormal rational functions
 Further improvement in matrix conditioning using orthonormal rational functions
 Z-domain (orthonormal) Vector Fitting

- Works on Excrete-time/Frequency systems Fast Vector Fitting Uses smart OR decomposition (compressions) for systems with many ports Eigenvalue-based Vector Fitting •
- Possibly with relative error minimization, for improved robustness
- Multivariate/Parameterized Vector Fitting
 Allows closed-form inclusion of geometry-material parameters in the macromodel equations Delayed Vector Fitting – Uses modified basis functions for representing propagation delays in closed form .
- Parallel Vector Fitting For multicore hardware architectures: close to ideal speedups, almost real-time modeling



Passivity: why?





Passivity conditions (scattering)

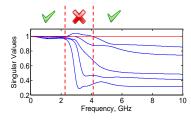
1.	$\mathbf{S}(-j\omega) = \mathbf{S}^*(j\omega)$									
	Guarantees real-valued impulse response. Always assumed by construction									
2.	$\ \mathbf{S}(j\omega)\ \le 1$ or $\max_i \sigma_i \{\mathbf{S}(j\omega)\} \le 1$									
	Energy condition: structure must not amplify signals. Sometimes called simply "passivity" condition									
3.	$\mathbf{S}(j\omega)$ is causal									

No anticipatory behavior in time-domain. Note: causality is a prerequisite for passivity! Guaranteed if macromodel is stable.



Passivity constraints (scattering)

$\mathbf{S}(s)$ is passive $\Leftrightarrow \{ \text{singular values of } \mathbf{S}(j\omega) \} \leq \mathbf{1}, \forall \omega$





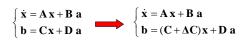
Passivity violations: why?

- · Data from measurement
 - Improper calibration and de-embedding, human mistakes
 - Measurement noise
- Data from simulation
 - Poor meshing
 - Inaccurate solver
 - Bad models or assumptions on material properties
 - Poor data post-processing algorithms
 - Putting together results from two solvers
- Macromodel
 - Approximation errors in Vector Fitting
 - May be critical out-of-band, where no data sample is available



Passivity enforcement

- Generate a new passive macromodel
- Apply small correction to preserve accuracy
 - original dataset should be passive
 - original macromodel should be accurate
 - (usually) preserve poles





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A case study: coupled Signal/Power Integrity

This case study courtesy of

- Georgia Institute of Technology, Atlanta GA, USA
- E-System Design, Inc.
 - Provided field solver Sphinx
- Politecnico di Torino

E-Surtem Derion

- IDEMWORKS

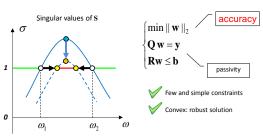
- IdemWorks s.r.l.
 - Provided passive macromodeling tool IdEM

www.e-systemdesign.com www.idemworks.com

 $\Delta \mathbf{S} = \Delta \mathbf{C} (s\mathbf{I} - \mathbf{A})^{-1} \mathbf{B}$



Model Perturbation



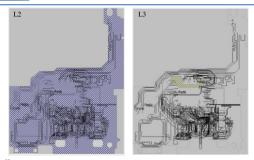


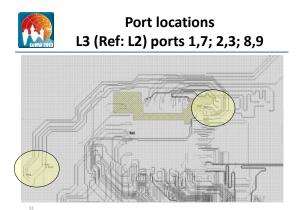
Board cross-section

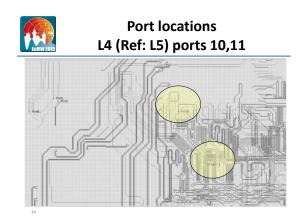
: 54	ction													
Subclass Name		e Type		Material		Thickness (MIL)	Conductivity (mho/on)	Dielectric Constant	Loss Targeri	Negative Adwark	Shield	Widh (MIL)		
1		SURFACE		SURFACE		AR				37	0			
2 T0P		CONDUCTOR	•	COPPER		1.25	595900	37	0	0		5.000		
3			•	FR-4		2.8	0	37	0.035					
4	L2		•	COPPER		0.7	595900	37	0		8			
5		CIELECTRIC	•	FR-6		2.8	0	37	0.035					
6	L3	CONDUCTOR		COPPER	•	0.7	592900	37	0			5.000		
2		DIFLECTRIC	-	FR-4		ť		37	0.035					
9	14	CONDUCTOR	•	COPPER	•	0.7	595300	37	0	D		5.000		
9		DIFFECTAC	•	FR-6		2.6	0	37	0.035					
ā.	15		•	COPPER		1.2	535300	37	0					
		CHELECTRIC	-	FR-4		3.5	0	37	0.035					
2	L6		•	COPPER	٠	1.2	191900	37	0	D				
5			-	FR-4		2		37	0.035					
8	LGA		•	COPPER		1.2	595900	4.5	0					
5		CIELECTRIC	•	FR-4	٠	4	0	37	0.035					
6	L7A		•	COPPER		1.2	\$99900	4.5	0		×			
2			•	FB-6		2	0	37	0.035					
3	17	PLANE	•	COPPER	*	1.2	595900	37	0	0				
9			•	FB-4		3.5		3.7	0.075					
2	LB	PLANE		DOPPER		1.2	535300	37	0		×			
		CHELECTRIC	•	FR-4		3.6	0	37	0.035					
2	L9	DONDUCTOR	•	COPPER		0.7	595900	37	0			5.000		
3		CHELECTRIC	•	FB-4		£.	0	37	0.035					
4	L10	CONDUCTOR	*	COPPER		0.7	595900	37	0			5.000		
5			•	FR-4		2.8	0	37	0.035					
6	L11		•	COPPER		0.7	\$99900	3.7	0					
2		CHELECTRIC	*	FR-4		2.8	0	37	0.035					
8	801TOM	CONDUCTOR		COPPER		1.25	595900	37	0			5.000		
<u>5</u>				A/R				37	0					

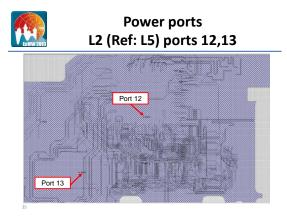


Layers L2 and L3

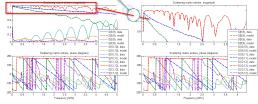








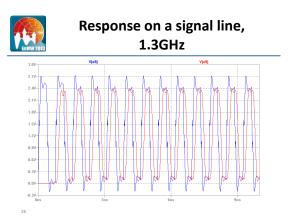


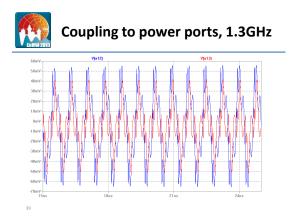


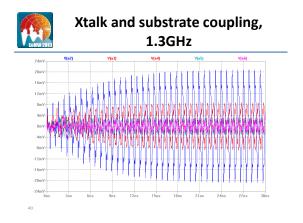


SPICE: excitation on signal lines



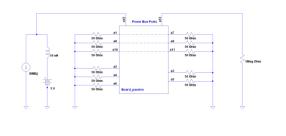


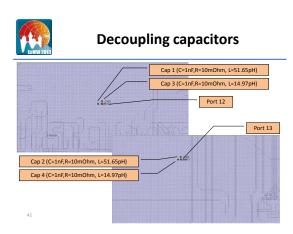






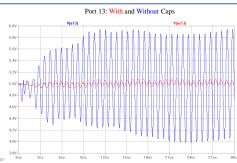
SPICE: excitation on PDN (core switching)





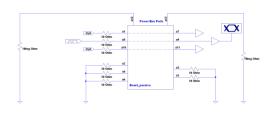


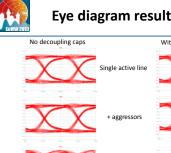
PDN response



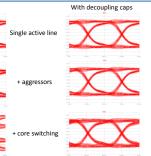


Eye diagram simulation: setup





Eye diagram results, 2.6 Gb/s





"Signal Integrity Summary"

Application:

- Fast numerical assessment of Signal and Power Integrity problems during early design stages
- Problems:
 - Mixing time-domain circuit-level models (NL) with frequencydomain description of interconnect networks, complexity, efficiency
- Solution:
 - Rational black-box macromodeling + smart implementation
 - · Key enabling factors for fast system-level simulation, design optimization, what-if analyses

October 7, 2013 Christian Schuste